

Features

- Current- I_{GT} : 200 μ A
- I_{RMS} : 0.8 A
- V_{RRM}/V_{DRM} : 400 V
- Operating and storage junction temperature range
 T_J, T_{stg} : -55°C to +150°C



Typical Applications

- Motor control
- Line-powered consumer applications
- Capacitive discharge ignitions



Absolute Maximum Ratings (unless otherwise specified)

Symbol	Parameter	NYC0102BLT1G	Unit
V_{DRM}	Repetitive Peak Off-stage Voltage	400	V
I_{TRMS}	Collector-Base Voltage	0.8	A
I_{DM}	Gate Trigger Current	200	μ A
P_D	Junction Temperature Range	+150	W
T_J/T_{STG}	Storage Temperature Range	-55 to +150	°C

Thermal Resistance Ratings

Symbol	Parameter	Maximum	Units
$R_{\theta Ja}$	Maximum Junction-to-Ambient	400	°C/W
$R_{\theta Jc}$	Maximum Junction-to-Case	15	°C/W

Electrical Characteristics (T_J =25°C unless otherwise specified)

Symbol	Parameter	Test Conditions		Min.	Max.	Units
VTM *	On state voltage	I _{TM} =1A			1.7	V
VGT	Gate trigger voltage	V _{AK} =7V			0.8	V
VDRM AND VRRM	Peak Repetitive forward and reverse blocking voltage	I _{DRM} = 10 μA		400		V
IDRM IRRM	Peak forward or reverse blocking Current	V _{AK} = Rated VDRM or VRRM, RGK=1kΩ	TC=25°C TC=125°C		10 100	uA
ITSM	Non-repetitive surge peak On-state current (T _J =25°C)	tp=10ms			9	A
		tp=8.3ms			10	
IGM	Peak Gate Current	Pulse Width≤1.0μs, TA=25°C			1	A
PGM	Peak Gate Power	Pulse Width≤1.0μs, TA=25°C			0.1	W
I _H	Holding current	I _{HL} = 20mA, V _{AK} = 7V			5	mA
IGT	Gate trigger current	V _{AK} =7V	A2		15	uA
			A1		30	uA
			A		80	uA
			B		200	uA
dV/dt	Critical Rate of Rise of Off-State Voltage	VD=Rated VDRM, Exponential Waveform, RGK=1000Ω, T _J =110°C		20	50	V/μs
di/dt	Critical Rate of Rise of On-State Current	IPK=20A; Pw=10usec. diG/dt=1A/μsec, Igt=20mA			50	A/μs

* Forward current applied for 1 ms maximum duration , duty cycle≤1% 。

TYPICAL CHARACTERISTICS @ Ta=25°C unless otherwise specified

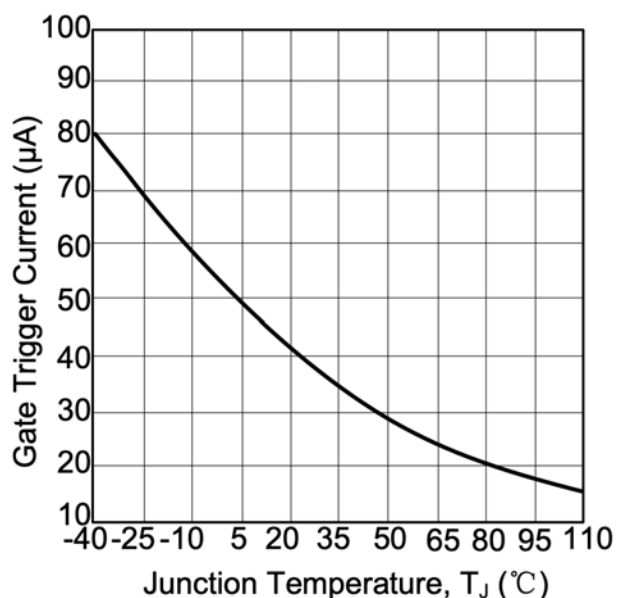


Fig 1. Typical Gate Trigger Current vs. Junction Temperature

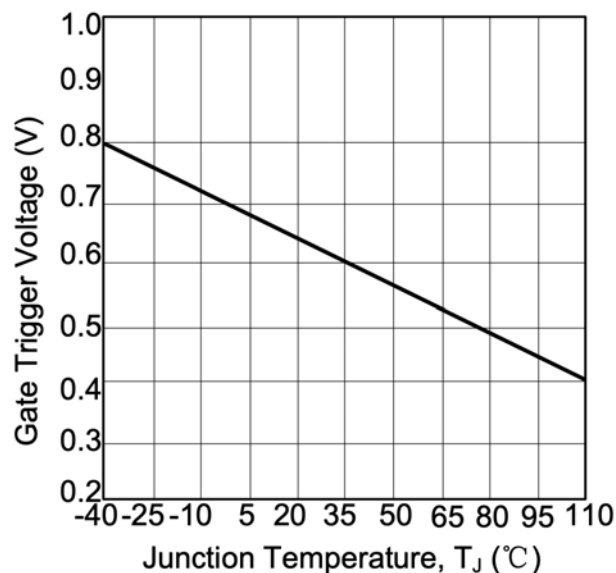


Fig 2. Typical Gate Trigger Voltage vs. Junction Temperature

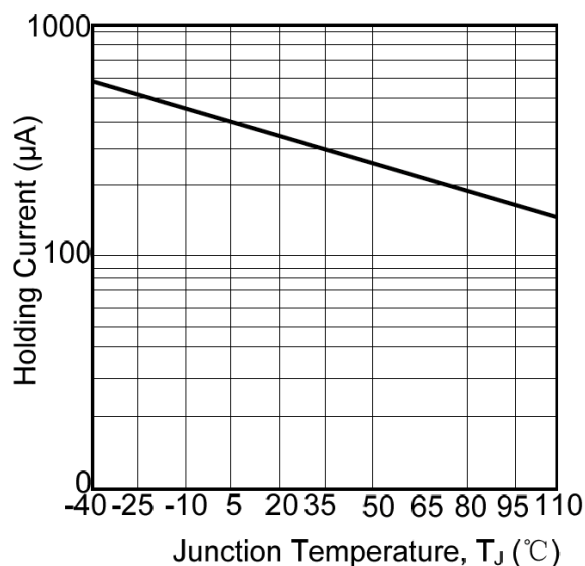


Fig 3. Typical Holding Current vs. Junction Temperature

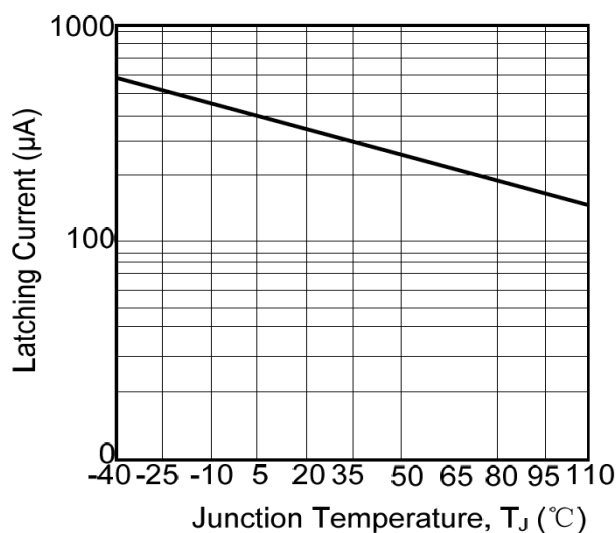
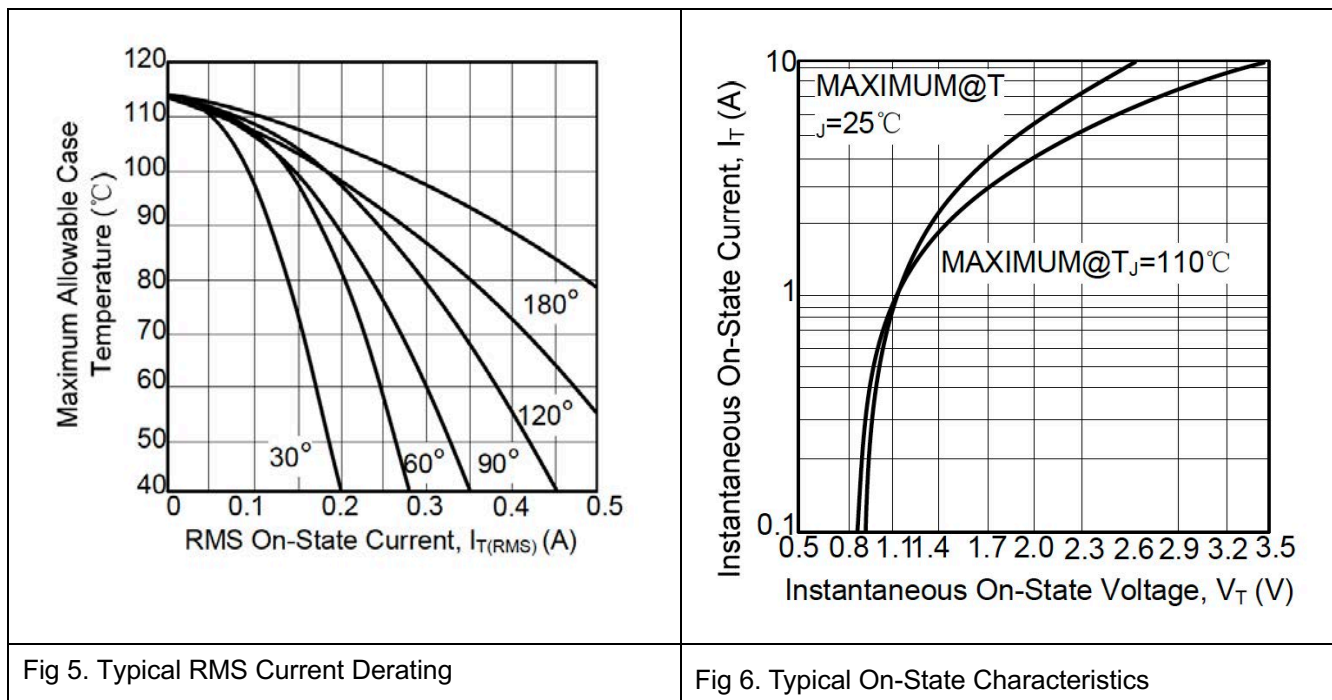
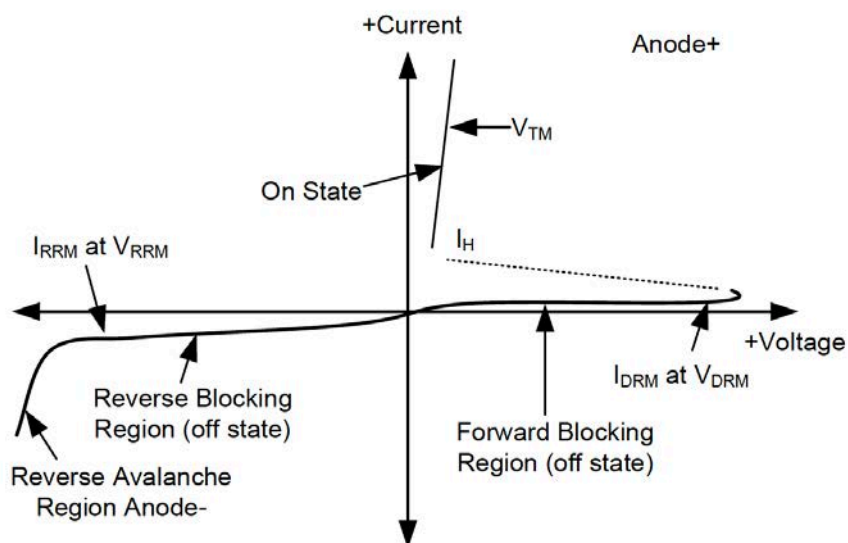


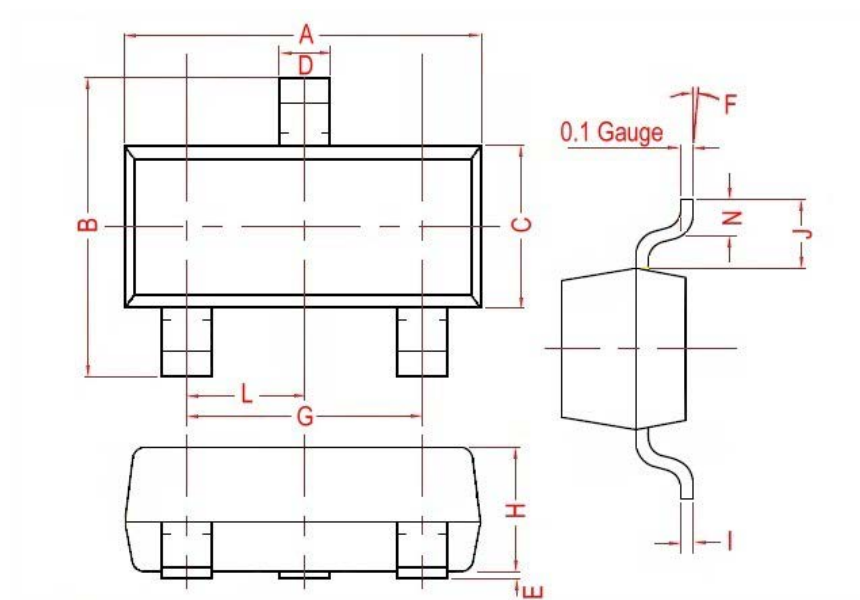
Fig 4. Typical Latching Current vs. Junction Temperature



Symbol	Parameter
V_{DRM}	Peak Repetitive Off Stat Forward Voltage
I_{DRM}	Peak Forward Blocking Current
V_{RRM}	Peak Repetitive Off State Reverse Voltage
I_{RRM}	Peak Reverse Blocking Current
V_{TM}	Peak On State Voltage
I_H	Holding Current



Package Dimension



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.70	3.10	G	1.90 Ref.	
B	2.30	3.00	H	0.90	1.30
C	1.20	1.75	I	0.05	0.21
D	0.30	0.50	J	0.58 Ref.	
E	0.01	0.15	L	0.95 Typ.	
F	0°	10°	N	0.20 Min.	

CCS Semiconductor and  are trademarks of Semiconductor Components Industries, CCS Semiconductor reserves the right to make changes without further notice to any products herein. CCS Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does CCS Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. CCS Semiconductor does not convey any license under its patent rights nor the rights of others.